SFI Test Report
TLK10232

Communication Interface – CIF
May 2014
Transmitter Performance Report
Test Setup

- TLK10232 is configured to supply a compliant SFI eye.
  - Data Rate: 10.3125Gbps
  - Output Swing: 660mV
  - Test Pattern: Valid 64/66B Traffic

- Eye mask used for this test is compliant the SFF-8431 standard (Rev 4.1).
  - Eye Mask Specification used during testing is Host Transmitter Output at compliance point B.
Transmitter Output Eye Diagram @ 25°C
Transmitter Output Eye Diagram @ 85°C
Transmitter Output Eye Diagram @ -40°C
Optical Module Interoperability Report
Test Setup

Test Board A

Test Board B

Single Mode Fiber
# Interoperability Testing Results

<table>
<thead>
<tr>
<th>Optical Module A</th>
<th>Optical Module B</th>
<th>BER Achieved</th>
<th>Data Rate</th>
</tr>
</thead>
<tbody>
<tr>
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For Further Information Contact:

Texas Instruments
CIF – Communication Interface

http://e2e.ti.com/support/interface/high_speed_interface/default.aspx
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